Peak EMI Reducing Solution

Features

- FCC approved method of EMI attenuation.
- Generates a 1X low EMI spread spectrum clock of the input frequency.
- Input frequency range: 12MHz to 22MHz.
- Internal loop filter minimizes external components and board space.
- Frequency deviation: - 0.8%(Typ) @20MHz.
- Low cycle-to-cycle jitter.
- 5.0V ± 5% operating voltage range.
- TTL or CMOS compatible outputs.
- Available in 8-pin SOIC and TSSOP Packages.

Product Description

The ASM3P2107A is a versatile spread spectrum frequency modulator designed specifically for input clock frequencies from 12MHz to 22MHz. The ASM3P2107A can generate an EMI reduced clock from crystal, ceramic resonator, or system clock.

The ASM3P2107A reduces electromagnetic interference (EMI) at the clock source, allowing system wide reduction of EMI of down stream clock and data dependent signals. The ASM3P2107A allows significant system cost savings by reducing the number of circuit board layers ferrite beads, shielding and other passive components that are traditionally required to pass EMI regulations.

The ASM3P2107A uses the most efficient and optimized modulation profile approved by the FCC and is implemented in a proprietary all digital method.

The ASM3P2107A modulates the output of a single PLL in order to "spread" the bandwidth of a synthesized clock, and more importantly, decreases the peak amplitudes of its harmonics. This results in significantly lower system EMI compared to the typical narrow band signal produced by oscillators and most frequency generators. Lowering EMI by increasing a signal's bandwidth is called 'spread spectrum clock generation'.
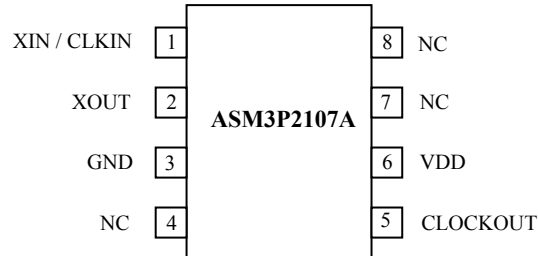
Applications

The ASM3P2107A is targeted towards EMI management for high speed digital applications such as PC peripheral devices, consumer electronics and embedded controller systems.

Block Diagram

rev 0.3
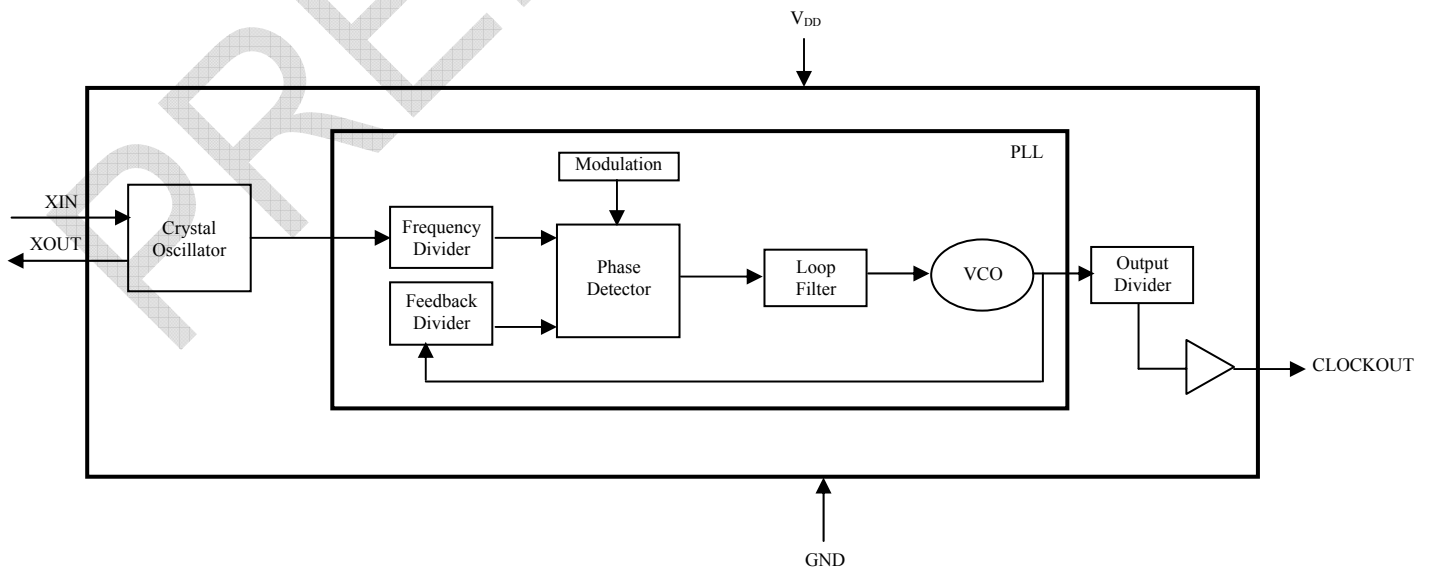
Pin Configuration

Pin Description

Pin#	Pin Name	Type	Description
1	XIN/CLKIN	I	Crystal connection or external reference frequency input. This pin has dual functions. It can be connected to either an external crystal or an external reference clock.
2	XOUT	O	Crystal connection. If using an external reference, this pin must be left unconnected.
3	GND	P	Ground to entire chip.
4	NC	-	No connect.
5	CLOCKOUT	O	Spread spectrum low EMI output.
6	VDD	P	Power supply for the entire chip (5V).
7	NC	-	No connect.
8	NC	-	No connect.

rev 0.3

Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
V_{DD}, V_{IN}	Voltage on any pin with respect to Ground	-0.5 to +7.0	V
T_{STG}	Storage temperature	-65 to +125	°C
T_A	Operating temperature	0 to 70	°C
T_s	Max. Soldering Temperature (10 sec)	260	°C
T_J	Junction Temperature	150	°C
T_{DV}	Static Discharge Voltage (As per JEDEC STD22- A114-B)	2	KV

Note: These are stress ratings only and are not implied for functional use. Exposure to absolute maximum ratings for prolonged periods of time may affect device reliability.

DC Electrical Characteristics

Symbol	Parameter	Min	Typ	Max	Unit
V_{IL}	Input low voltage	GND – 0.3	-	0.8	V
V_{IH}	Input high voltage	2.0	-	V_{DD} + 0.3	V
I_{IL}	Input low current	-	44	-	µA
I_{IH}	Input high current	-	66	-	µA
I_{XOL}	X_{OUT} output low current (@ 0.4, V_{DD} = 5V)	-	3	-	mA
I_{XOH}	X_{OUT} output high current (@2.5V, V_{DD} = 5V)	-	3	-	mA
V_{OL}	Output low voltage (V_{DD} = 5V, I_{OL} = 20mA)	-	-	0.4	V
V_{OH}	Output high voltage (V_{DD} = 5V, I_{OH} = 20mA)	2.5	-	-	V
I_{CC}	Dynamic supply current normal mode (5V, 18MHz and 15pF loading)	-	40	-	mA
I_{DD}	Static supply current standby mode	-	40	-	µA
V_{DD}	Operating voltage	4.75	5.0	5.25	V
t_{ON}	Power up time (first locked clock cycle after power up)	-	0.18	-	mS
Z_{OUT}	Clock out impedance	-	50	-	Ω

AC Electrical Characteristics

| Symbol	Parameter		Min	Typ	Max	Unit
f_{IN}	Input frequency		12	-	22	MHz
MODOUT	Output frequency		12	-	22	MHz
f_d	Frequency Deviation	Input Frequency =12MHz	-	-2.13	-	%
		Input Frequency =22MHz	-	-0.62	-	
t_{LH}*	Output rise time (measured at 0.8V to 2.0V)		-	440	-	pS
t_{HL}*	Output fall time (measured at 2.0V to 0.8V)		-	300	-	pS
t_{JC}	Jitter (cycle to cycle)		-	-	360	pS
t_D	Output duty cycle		45	50	55	%

* V_{DD} = +5V, Input Frequency = 18MHz, t_{LH} and t_{HL} are measured into a capacitive load of 15pF
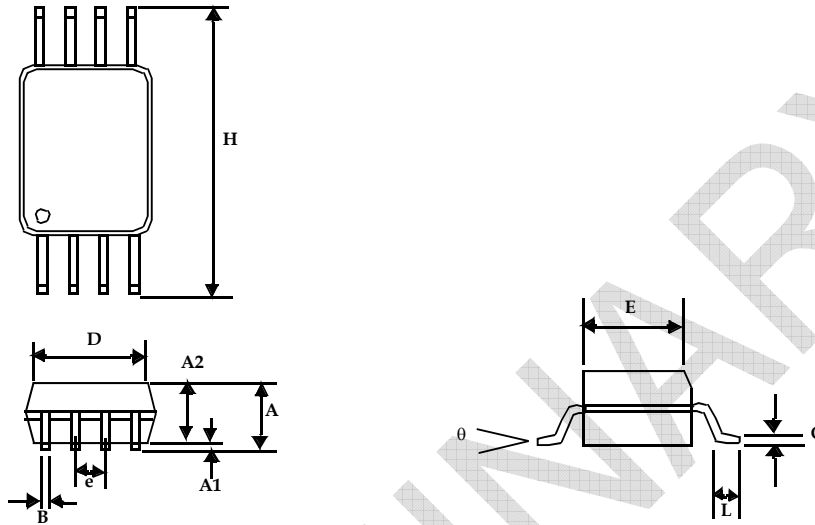
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Package Information

8-Pin SOIC Package
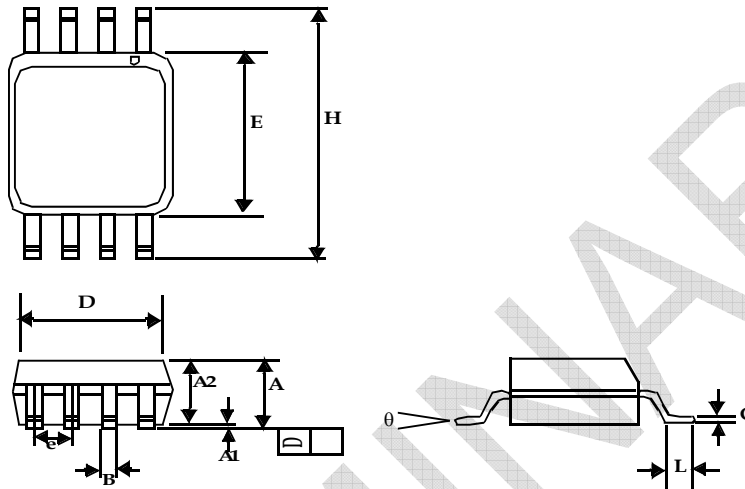
Symbol	Dimensions			
	Inches		Millimeters	
	Min	Max	Min	Max
A1	0.004	0.010	0.10	0.25
A	0.053	0.069	1.35	1.75
A2	0.049	0.059	1.25	1.50
B	0.012	0.020	0.31	0.51
C	0.007	0.010	0.18	0.25
D	0.193 BSC		4.90 BSC	
E	0.154 BSC		3.91 BSC	
e	0.050 BSC		1.27 BSC	
H	0.236 BSC		6.00 BSC	
L	0.016	0.050	0.41	1.27
θ	0°	8°	0°	8°

8-Pin TSSOP Package

Symbol	Dimensions			
	Inches		Millimeters	
	Min	Max	Min	Max
A		0.043		1.10
A1	0.002	0.006	0.05	0.15
A2	0.033	0.037	0.85	0.95
B	0.008	0.012	0.19	0.30
c	0.004	0.008	0.09	0.20
D	0.114	0.122	2.90	3.10
E	0.169	0.177	4.30	4.50
e	0.026 BSC		0.65 BSC	
H	0.252 BSC		6.40 BSC	
L	0.020	0.028	0.50	0.70
θ	0°	8°	0°	8°

Ordering Codes

Part Number	Marking	Package	Temperature
ASM3P2107AF-08-SR	3P2107AF	8-PIN SOIC, TAPE AND REEL, Pb Free	Commercial
ASM3P2107AF-08-ST	3P2107AF	8-PIN SOIC, TUBE, Pb Free	Commercial
ASM3P2107AF-08-TR	3P2107AF	8-PIN TSSOP, TAPE AND REEL, Pb Free	Commercial
ASM3P2107AF-08-TT	3P2107AF	8-PIN TSSOP, TUBE, Pb Free	Commercial
ASM3P2107AG-08-SR	3P2107AG	8-PIN SOIC, TAPE AND REEL, Green	Commercial
ASM3P2107AG-08-ST	3P2107AG	8-PIN SOIC, TUBE, Green	Commercial
ASM3P2107AG-08-TR	3P2107AG	8-PIN TSSOP, TAPE AND REEL, Green	Commercial
ASM3P2107AG-08-TT	3P2107AG	8-PIN TSSOP, TUBE, Green	Commercial
ASM3P2107A-08-SR	3P2107A	8-PIN SOIC, TAPE AND REEL	Commercial
ASM3P2107A-08-ST	3P2107A	8-PIN SOIC, TUBE	Commercial
ASM3P2107A-08-TR	3P2107A	8-PIN TSSOP, TAPE AND REEL	Commercial
ASM3P2107A-08-TT	3P2107A	8-PIN TSSOP, TUBE	Commercial

Device Ordering Information

A S M 3 P 2 1 0 7 A G - 0 8 - S T

R = Tape & reel, T = Tube or Tray

O = SOT	U = MSOP
S = SOIC	E = TQFP
T = TSSOP	L = LQFP
A = SSOP	U = MSOP
V = TVSOP	P = PDIP
B = BGA	D = QSOP
Q = QFN	X = SC-70

DEVICE PIN COUNT

F = LEAD FREE AND RoHS COMPLIANT PART
G = GREEN PACKAGE

PART NUMBER

X= Automotive   I= Industrial   P or n/c = Commercial
   (-40C to +125C)   (-40C to +85C)   (0C to +70C)

1 = Reserved	6 = Power Management
2 = Non PLL based	7 = Power Management
3 = EMI Reduction	8 = Power Management
4 = DDR support products	9 = Hi Performance
5 = STD Zero Delav Buffer	0 = Reserved

ALLIANCE SEMICONDUCTOR MIXED SIGNAL PRODUCT

Licensed under US patent #5,488,627, #6,646,463 and #5,631,920.

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Note: This product utilizes US Patent # 6,646,463 Impedance Emulator Patent issued to Alliance Semiconductor, dated 11-11-2003

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7 of 7

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